

IN THE SPECIFICATION:

Paragraph beginning at page 14, line 12 has been amended as follows:

A connection of the bypass condensers by the condenser chip is the same as that of the structure shown in Figs. 3A and 3B. In the third embodiment, however, electrode pads 10Bc, which are provided on the condenser chip 10B, and electrode pads [[10Ac]] 1Aa, which are provided on the semiconductor chip 1A, are connected through bonding wires 14.

Paragraph beginning at page 15, line 5 has been amended as follows:

According to the above-mentioned connecting method, four electrode pads 1Ac on the semiconductor chip 1A and four electrode pads 10Bc on the condenser chip 10B are connected through the bonding wires 14. Here, the lowermost electrode pad 10Bc among the four electrode pads 10Bc in Fig. 7A is connected to the power supply line (Vcc line) 8 within the semiconductor chip 1A. Thus, the electrode pad [[10Aa]] 1Aa serving as the power supply terminal is connected to the power supply line 8 through eight bonding wires 14. The eight bonding wires 14 mentioned before act as an inductor, which is connected to the power supply line so as to attenuate a high frequency component on the power supply line, and reduces a noise.